



Shenzhen Flourish Electronics Co., LTD

(C) D- C



SPECIFICATION FOR APPROVAL



Shenzhen Flourish Electronics Co., LTD

(C) D- C

Features

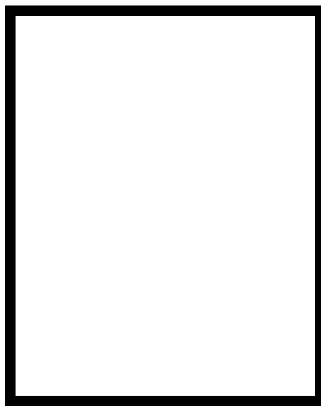
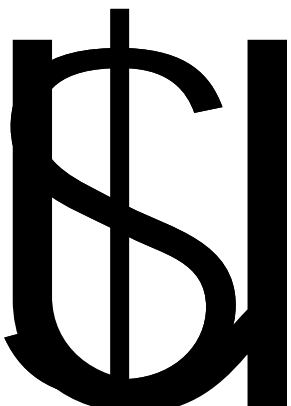


Test Condition



Shenzhen Flourish Electronics Co., LTD

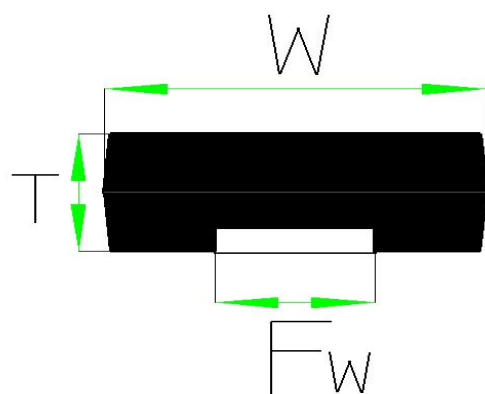
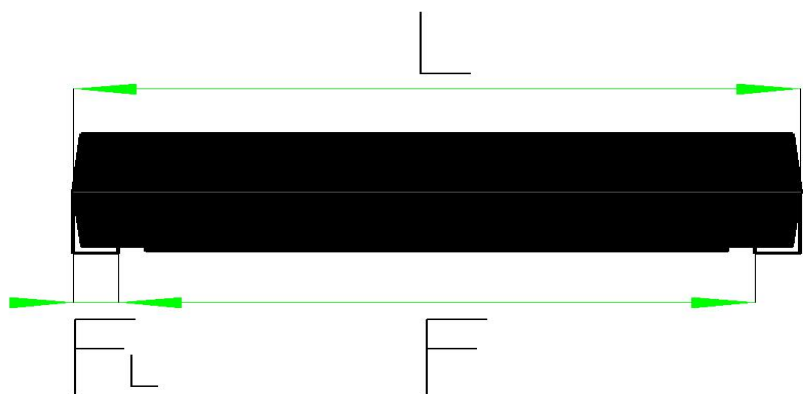
(C) D- C





Shenzhen Ffourish Electronics Co., LTD

(C) D- C



	±	±	±	±	±	±

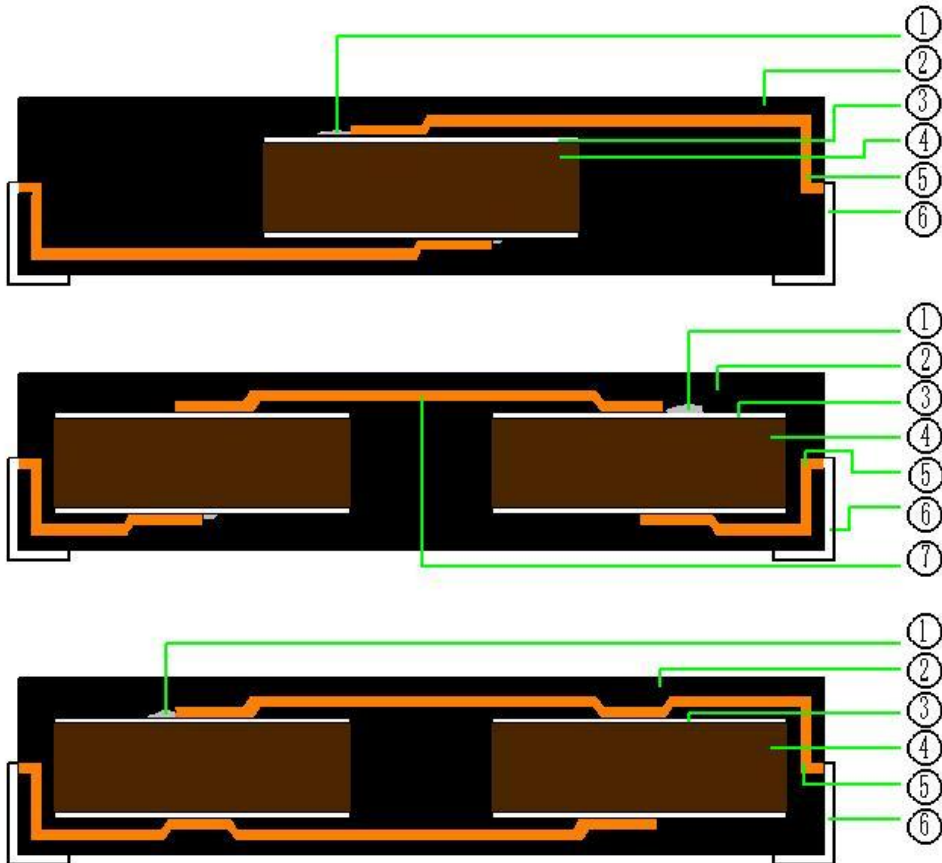


(Marking Explain)

Safety Certification:

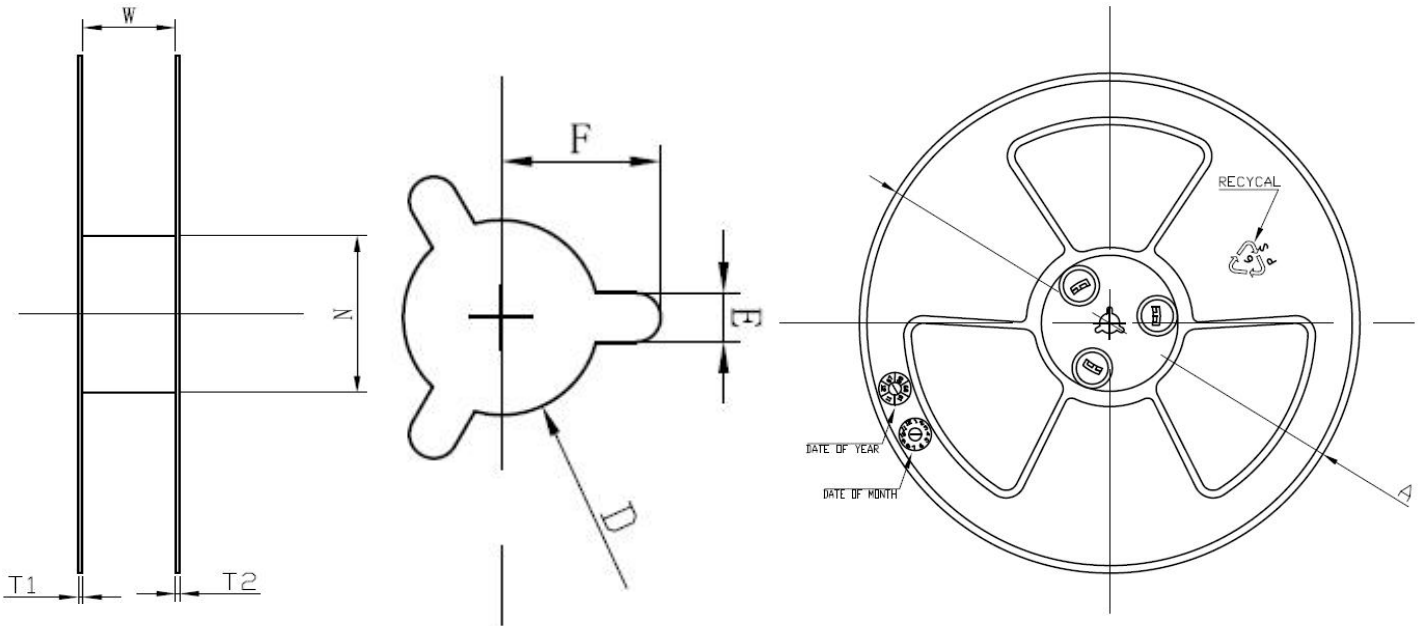
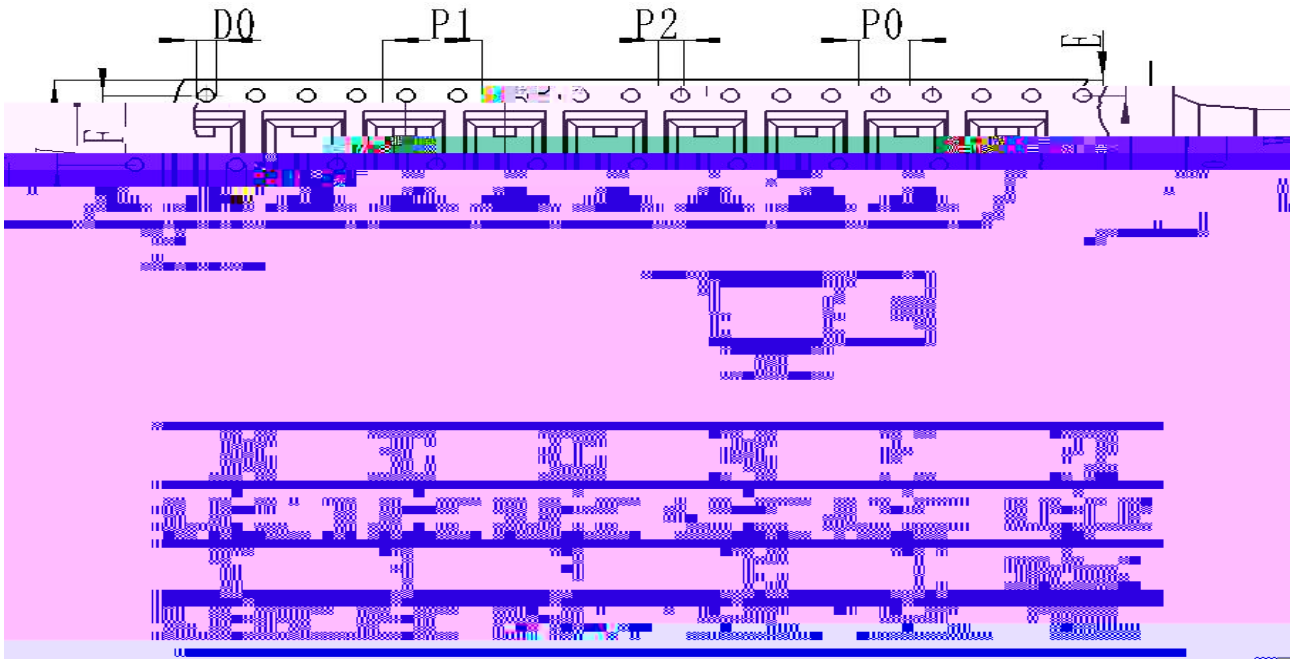


Structure

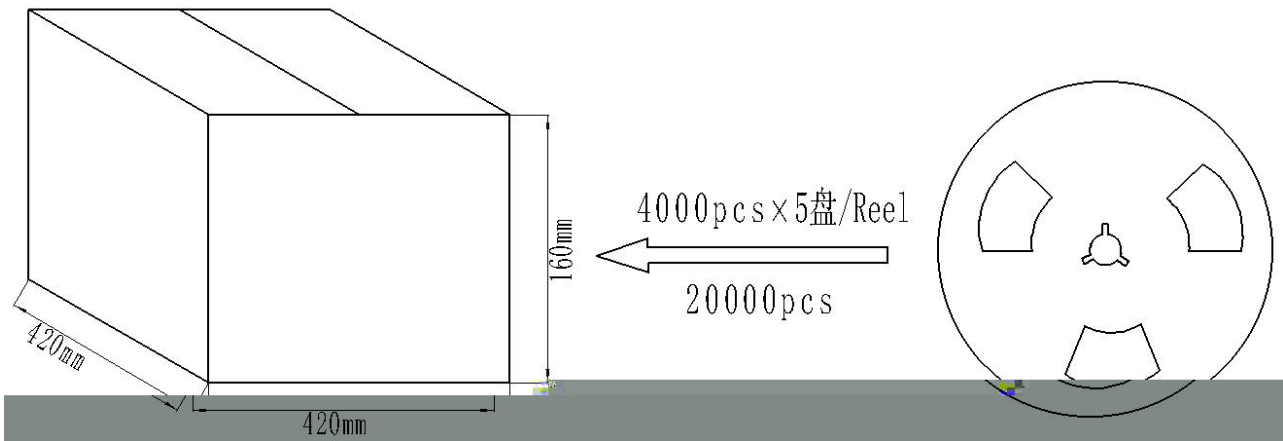


packing description

6.1



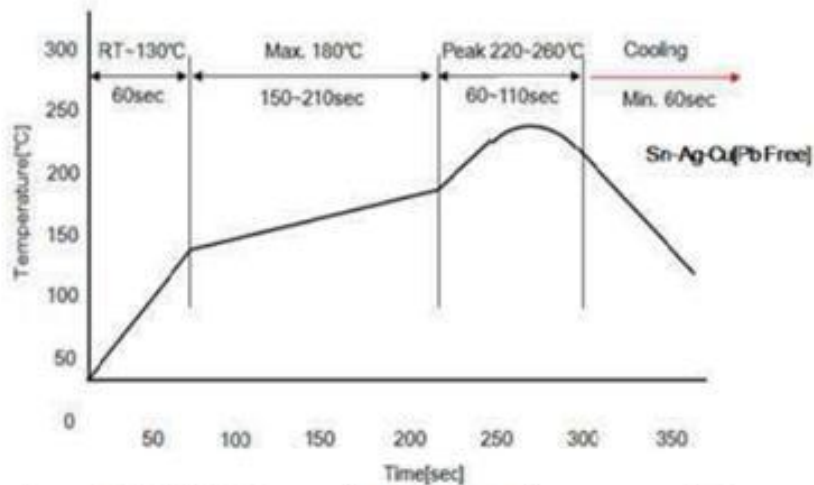
	±	±	±	±	±	±	±	±



Welding according to the instruction

7.1

☆ 回流焊接曲线



温区	温度范围 (°C)	时间 (sec)	备注
a	RT~130	60	焊锡: Sn-Ag-Cu 高温时间: < 10 sec
b	180 max	150~210	
c	220~260(260 max)	60~110	
d	220~RT	60 min	

当焊接温度低于锡的熔点时，贴片镀锡端子的可焊性将下降。使用之前请确认贴片镀锡电极的可焊性
焊接区出风口及内部空间最高温度不能超过 280°C，温度超过时，会造成产品发生失效。由于超温使用所造成的不良，我司不予承担责任。



Shenzhen Flourish Electronics Co., LTD

(C) D- C

7.2.

!

! ()

Level	Bake@40C 5%RH	
	Saturated@30C/85%RH	At limit of Floor life+72hr@30C/60RH
3	79days	67days

!

!



Shenzhen Flourish Electronics Co., LTD

(C) D- C

7.4

!

()